



INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁶ : H05B 1/02, B23K 10/00	A1	(11) International Publication Number: WO 99/45745 (43) International Publication Date: 10 September 1999 (10.09.99)
(21) International Application Number: PCT/US99/04619 (22) International Filing Date: 2 March 1999 (02.03.99) (30) Priority Data: 09/035,628 5 March 1998 (05.03.98) US (71) Applicant: FSI INTERNATIONAL, INC. [US/US]; 322 Lake Hazeltine Drive, Chaska, MN 55318-1096 (US). (72) Inventors: ARMSTRONG, Keith, H.; 1310 Grant, Sherman, TX 75092 (US). KEMP, Kevin, G.; 7029 Lattimore Drive, Dallas, TX 75252 (US). LIANG, Faqui (Frank); 8812 Christian Court, Plano, TX 75025 (US). RAMANAN, Natarajan; Apartment 1311, 5945 West Parker, Plano, TX 75093 (US). (74) Agent: KAGAN, David, B.; Faegre & Benson LLP, 2200 Norwest Center, 90 South Seventh Street, Minneapolis, MN 55402-3901 (US).	(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, UZ, VN, YU, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SL, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG). Published With international search report. Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments. *G00002*	
(54) Title: COMBINATION BAKE/CHILL APPARATUS INCORPORATING LOW THERMAL MASS, THERMALLY CONDUCTIVE BAKEPLATE		
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(57) Abstract Systems and methods that make it possible to rapidly cycle a workpiece (12) through a temperature/time profile over a wide temperature range, e.g., 0 °C to 350 °C, without having to lift and transfer the workpiece between separate baking and chilling mechanisms. The present invention is based in part upon the concept of using a low thermal mass, thermally conductive heating member (20) to support a workpiece, such as a microelectronic device, during both baking and chilling operations. While supporting the workpiece on one surface, the other surface of the heating member can be brought into and out of thermal contact with a relatively thermally massive chill plate (26) to easily switch between baking and chilling operations. A simple mechanism is all that is required to either physically separate the heating member (20) and chill plate (26) to accomplish the most rapid heating, or the simple mechanism adjoins the heating member and chill plate to accomplish the most rapid chilling. This approach completely eliminates the need to rely upon a workpiece handling mechanism in order to lift and transfer a microelectronic device from a heating member to a separate chill plate. This approach also allows both chilling and baking to occur from a direction below the microelectronic device.		